

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Krywanczyk et al.

Docket No. END920030041US1

Filed: 11/13/2003

Art Unit: 1763

Serial No.: 10/713,659

Examiner: Goudreau, George A.

For: Method for thinning wafers
that have contact bumps

Confirmation No.: 9863

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the non-final Office Action dated January 13, 2006, and identified as Paper No. 010906, please consider the following:

Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.